Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-88. (Cancelled)

89. (Previously Presented) A method for removably attaching a planarizing medium to a platen of a planarizing machine, comprising:

applying a signal to the platen that produces an electrostatic attractive force between the platen and the planarizing medium.

90. (Original) The method of claim 89, further comprising positioning the platen adjacent to the planarizing medium.

91. (Previously Presented) The method of claim 89 wherein the platen includes a conductive plate positioned within the platen, and applying a signal includes providing a signal to the conductive plate positioned within the platen.

92. (Previously Presented) The method of claim 89 wherein the planarizing medium includes a polishing pad and a support member and applying a signal includes applying a signal that produces an electrostatic attractive force between the platen and the support member.

93. (Previously Presented) The method of claim 89 wherein the planarizing medium includes a polishing pad having conductive particles and applying a signal includes applying a signal that produces an electrostatic attractive force between the platen and the conductive particles.

94. (Previously Presented) The method of claim 89 wherein applying a signal includes applying a voltage to the platen.

95-98. (Cancelled)

99. (Previously Presented) The method of claim 92, further comprising locking the support member to the platen with a locking device positioned on the support member that is engageably received by the platen.

100. (Previously Presented) A method for removably attaching a planarizing medium to a platen of a planarizing machine, comprising:

distributing a plurality of conductive particles in the planarizing medium; and

applying a signal to the platen that produces an electromagnetic attractive force between the platen and the conductive particles in the planarizing medium.

101. (Previously Presented) The method of claim 100, further comprising positioning the platen adjacent to the planarizing medium.

102. (Previously Presented) The method of claim 100 wherein the platen includes a conductive plate positioned within the platen, and applying a signal includes applying a signal to the conductive plate positioned within the platen.

103. (Previously Presented) The method of claim 100 wherein distributing a plurality of conductive particles further comprises distributing the plurality of conductive particles uniformly in the planarizing medium.

104. (Previously Presented) The method of claim 101 wherein distributing a plurality of conductive particles further comprises concentrating the plurality of conductive particles in a portion of the planarizing medium adjacent to the platen.

105. (Previously Presented) The method of claim 100 wherein distributing a plurality of conductive particles further comprises distributing a plurality of particles in the planarizing medium that are comprised of a ferrous material.

106. (Previously Presented) The method of claim 100, wherein applying a signal includes applying a current to the platen.

107. (Previously Presented) A method for releasably attaching a planarizing medium having a plurality of internally distributed conductive particles to a platen of a planarization machine, comprising:

positioning the planarization medium adjacent to the platen; and

coupling a signal to the platen to produce an electromagnetic attractive force between the conductive particles and the platen.

108. (Previously Presented) The method of claim 107, wherein the planarizing medium includes an attachment surface having a concentration of conductive particles located proximate to the attachment surface, and positioning the planarizing medium is further comprised of positioning the attachment surface on the platen.

109. (Previously Presented) The method of claim 107, wherein the platen includes a conductive member positioned within the platen, and coupling a signal to the platen further comprises coupling a signal to the conductive member.

110. (Previously Presented) The method of claim 107, wherein coupling a signal includes coupling a current to the platen.